



Material Content Data Sheet



Sales Product Name		SAK-XC2267-96F80L AC		Issued		25. September 2017		
MA#		MA001057084						
Package		PG-LQFP-100-3		Weight*		747.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	5.46	5.46	54643	54643
leadframe	inorganic material	phosphorus	7723-14-0	0.067	0.01		90	
	non noble metal	zinc	7440-66-6	0.270	0.04		361	
	non noble metal	iron	7439-89-6	5.396	0.72		7217	
wire	non noble metal	copper	7440-50-8	219.094	29.30	30.07	293031	300699
	noble metal	gold	7440-57-5	4.149	0.56	0.56	5550	5550
	organic material	carbon black	1333-86-4	2.290	0.31		3063	
encapsulation	plastics	epoxy resin	-	61.834	8.27		82701	
	inorganic material	silicondioxide	60676-86-0	393.906	52.68	61.26	526837	612601
leadfinish	non noble metal	tin	7440-31-5	8.282	1.11	1.11	11077	11077
plating	noble metal	silver	7440-22-4	1.060	0.14	0.14	1418	1418
glue	plastics	epoxy resin	-	2.619	0.35		3503	
	noble metal	silver	7440-22-4	7.858	1.05	1.40	10509	14012
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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